



Development of a High-Speed High- Performance Microfabricated Gas Chromatograph

SAND2007-0927C

Pittcon 2007 – Chicago, IL

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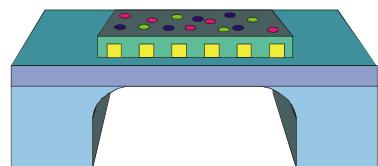
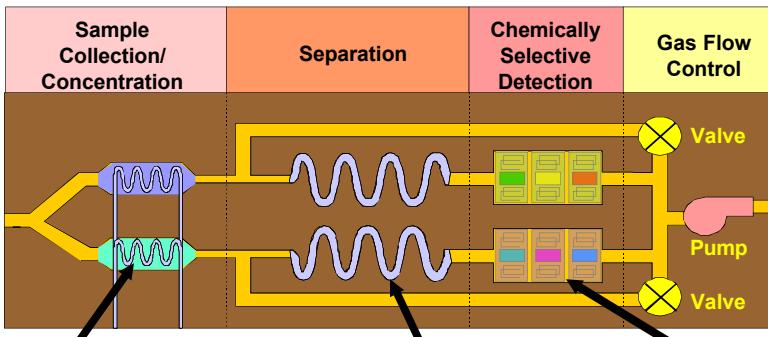


μ ChemLab™ at Sandia National Laboratories

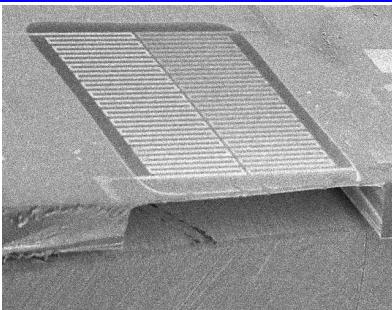
Hand-held chemical analysis system that uses three microfabricated stages.



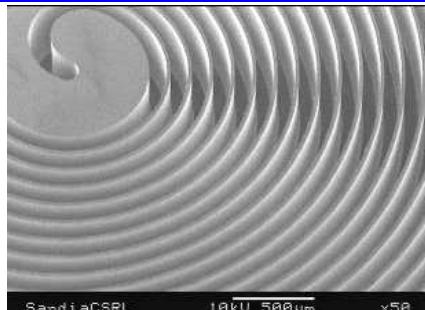
- 8" x 4" x 2"
- 2 min. analysis
- 4W max. power



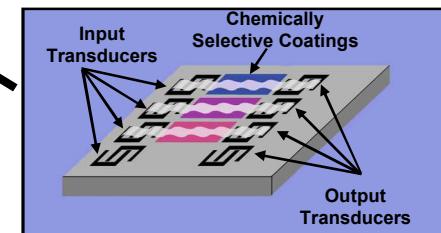
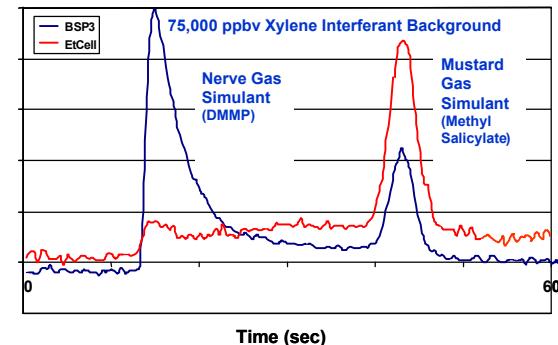
Preconcentrator accumulates species of interest



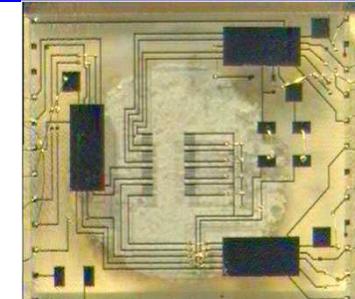
Gas Chromatograph separates species in time



Response



Acoustic Sensors provide sensitive detection



Over a decade of development in small, low power, selective gas chromatographs.

Next Generation Development Program Goals:

High Speed, High Performance GC

- Size
 - Small Size
 - **<20cm³ Total Volume**
 - MEMS Integrated Components
- Speed
 - High Speed Separations
 - **8 components separated from 8 interferences in 4s**
 - Hydrogen Carrier Gas
- Power
 - Low Power
 - **<3J/analysis**
 - Catalytic Combustion of hydrogen for heating column
- Resolution
 - High Performance
 - **Total Analytical Peak Capacity >100 in 4s**
 - High Aspect Ratio MEMS (HARM) columns





Modeling Predicts System Efficiency Using Rectangular GC Columns

1st 3 terms model column performance, 4th term connects column to system

$$H = \underbrace{\frac{2D_g f_1 f_2}{\bar{u}}}_{\text{Longitudinal diffusion}} + \underbrace{\frac{(1 + 9k + 25.5k^2)}{105(k+1)^2} \frac{w^2}{D_g} \frac{f_1}{f_2} \bar{u}}_{\text{Mass Transport in the Mobile Phase}} + \underbrace{\frac{2}{3} \frac{k}{(k+1)^2} \frac{(w+h)^2 d_f^2}{D_s h^2} \bar{u}}_{\text{Mass Transport in the Stationary Phase}} + \underbrace{\frac{\Delta t^2 u^2}{L(k+1)^2}}_{\text{Extra-Column Band Broadening}}$$

Longitudinal
diffusion

Mass Transport in the
Mobile Phase

Mass Transport in the
Stationary Phase

Extra-Column
Band Broadening

\bar{u} – average linear carrier gas velocity

h – channel height

D_g – binary diffusion coefficient in gas phase

d_f – stationary phase film thickness

f_1 – Giddings-Golay gas compression correction factor

D_s – binary diffusion coefficient in stationary phase

f_2 – Martin-James gas compression correction factor

L – column length

k – retention factor

Δt – time correlating to extra column band broadening

w – channel width

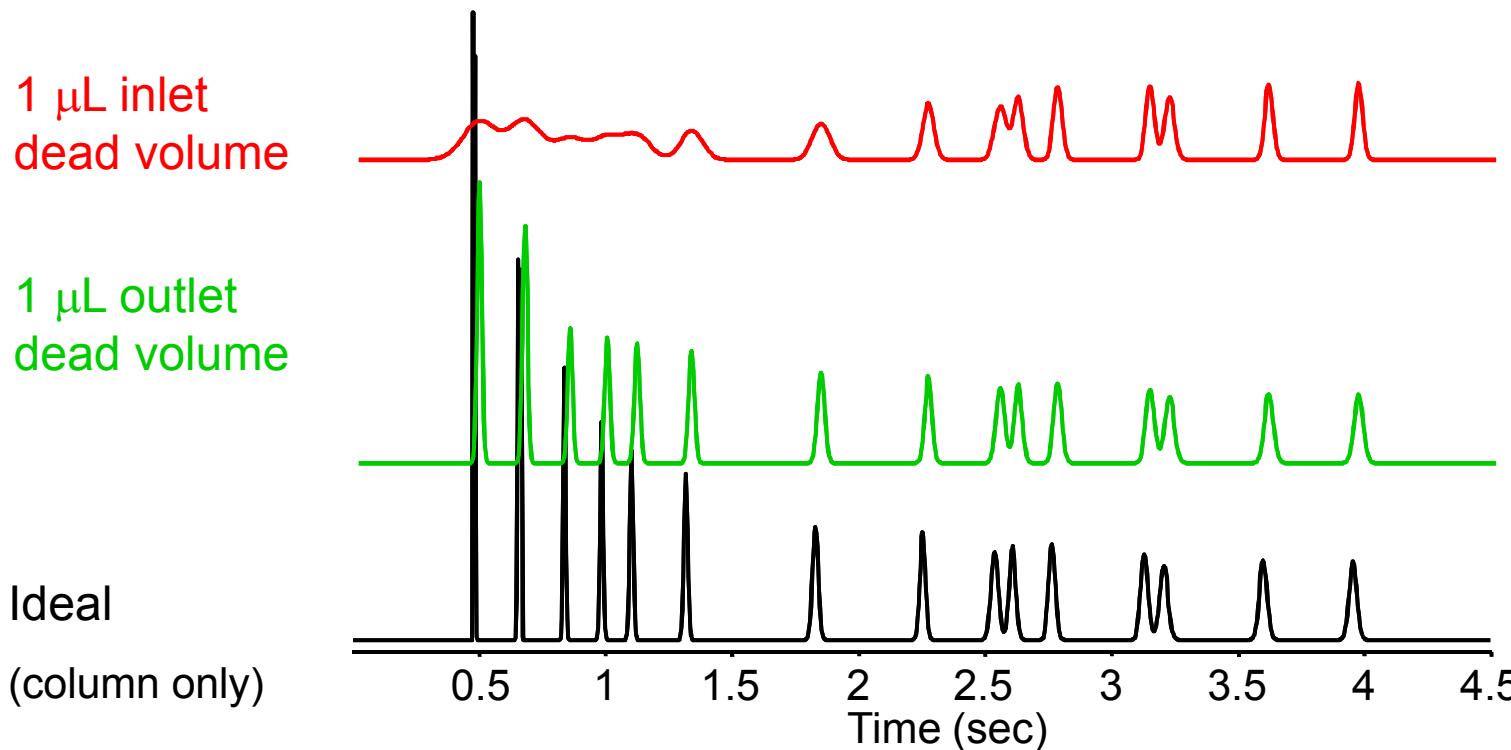
$\Delta t = \frac{\text{inlet (or outlet) volume, cm}^3}{\text{gas flow rate, cm}^3/\text{sec}}$



Integration Driver: Modeled GC Band Broadening

Ahn and Brandani Model – Dec. 2005

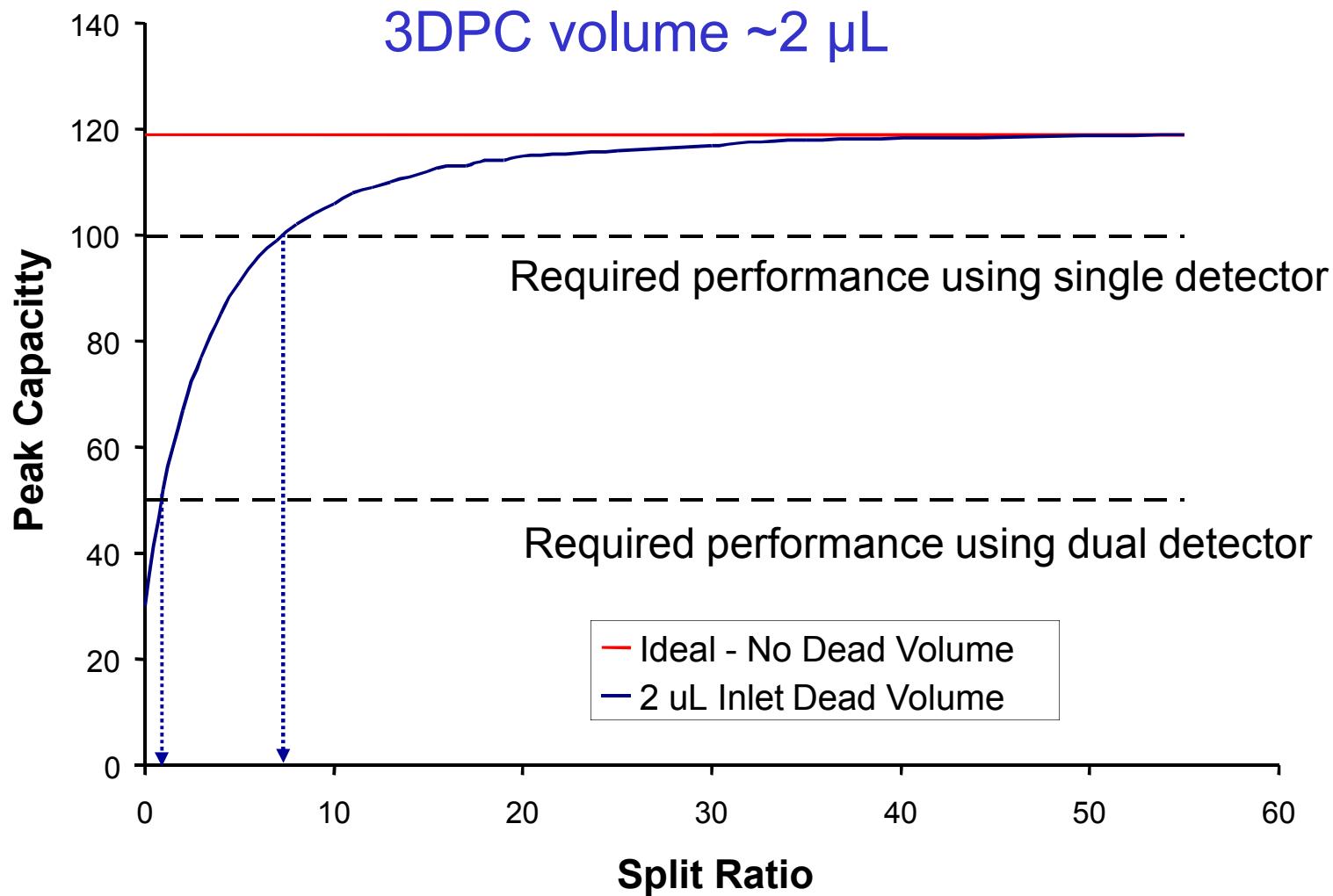
T-programmed 8/8 separation



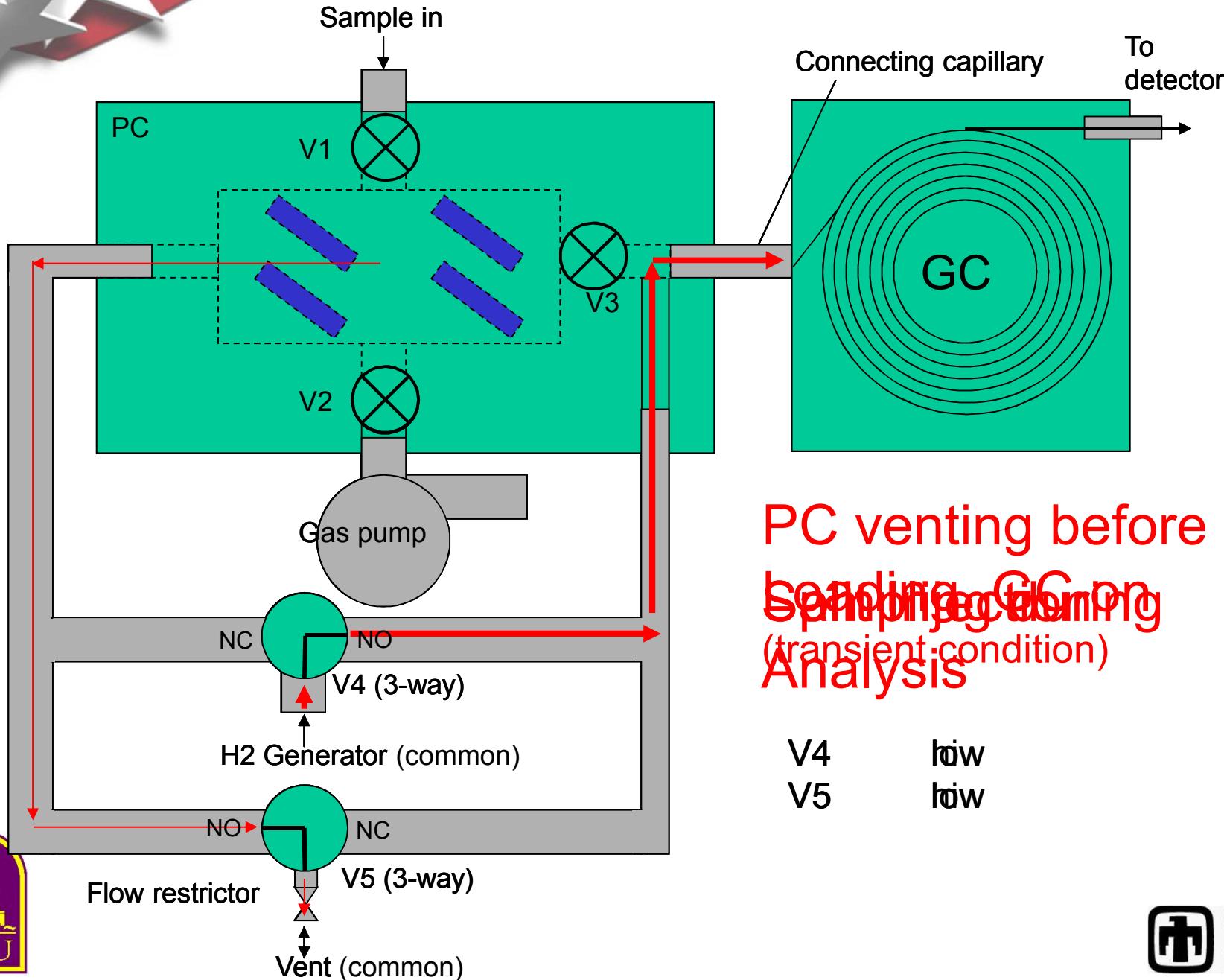
Inlet dead volume costs more than outlet dead volume due to carrier gas compressibility: $(\text{cm}^3/\text{sec})_{\text{outlet}} > (\text{cm}^3/\text{sec})_{\text{inlet}}$



Mitigating the Effects of Inlet Dead Volume GC Peak Capacity vs. Injection Split Ratio



2 External Valve System Schematic



PC venting before boiling-off spray cooling (transient condition) Analysis

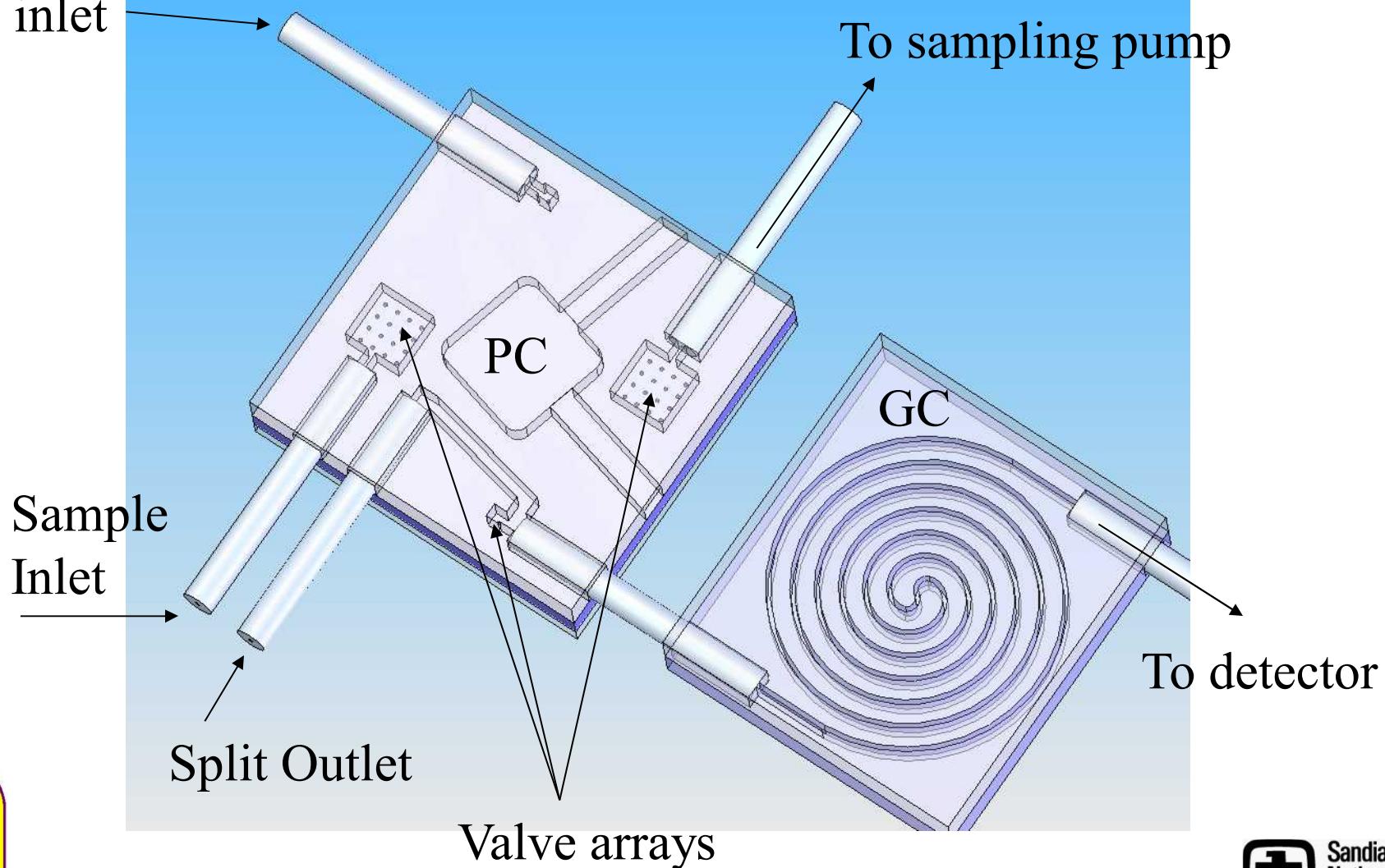
V4 low
V5 low



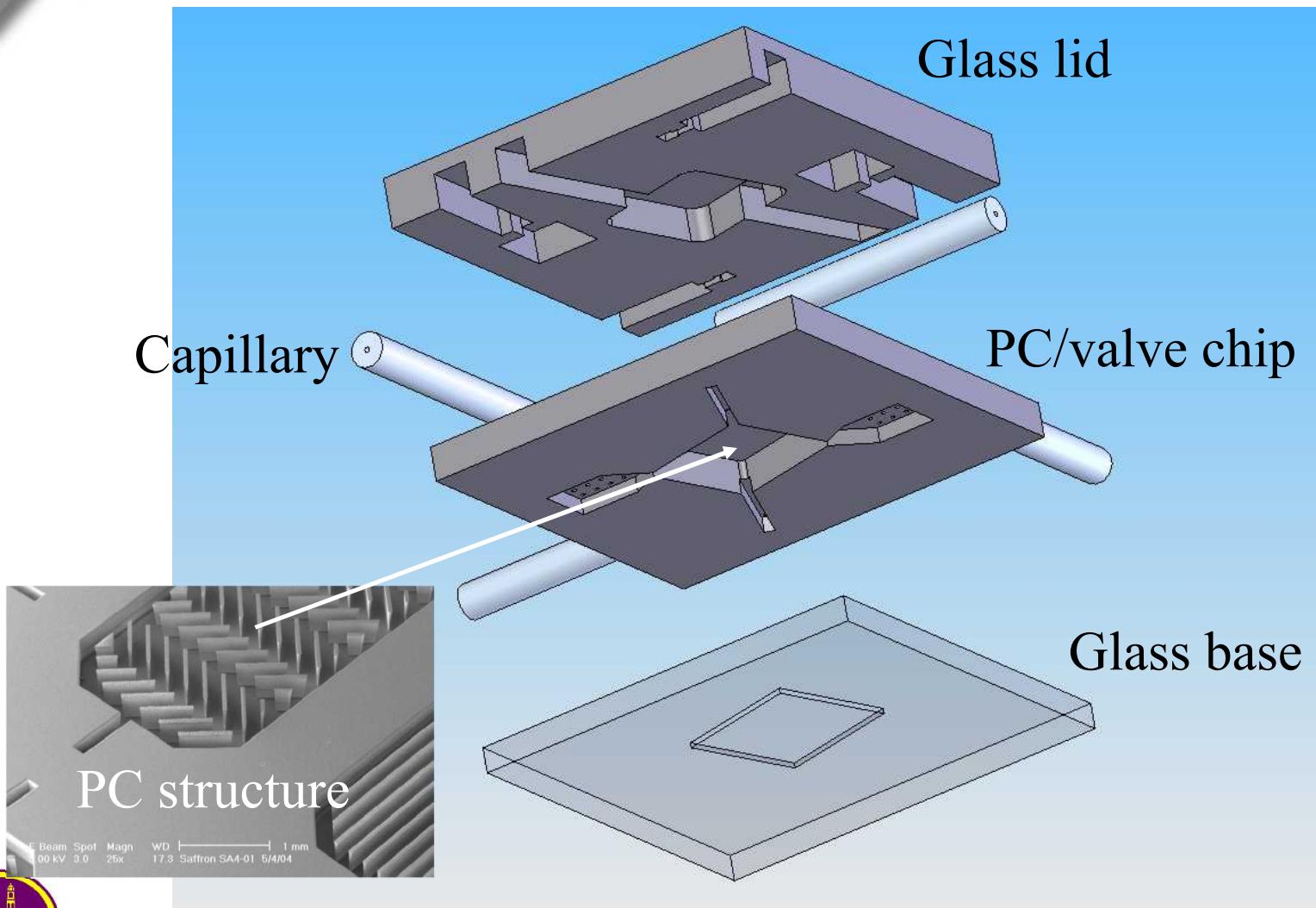
Hybrid Integration

MEMS valves on PC chip limit inlet volume

H_2 inlet

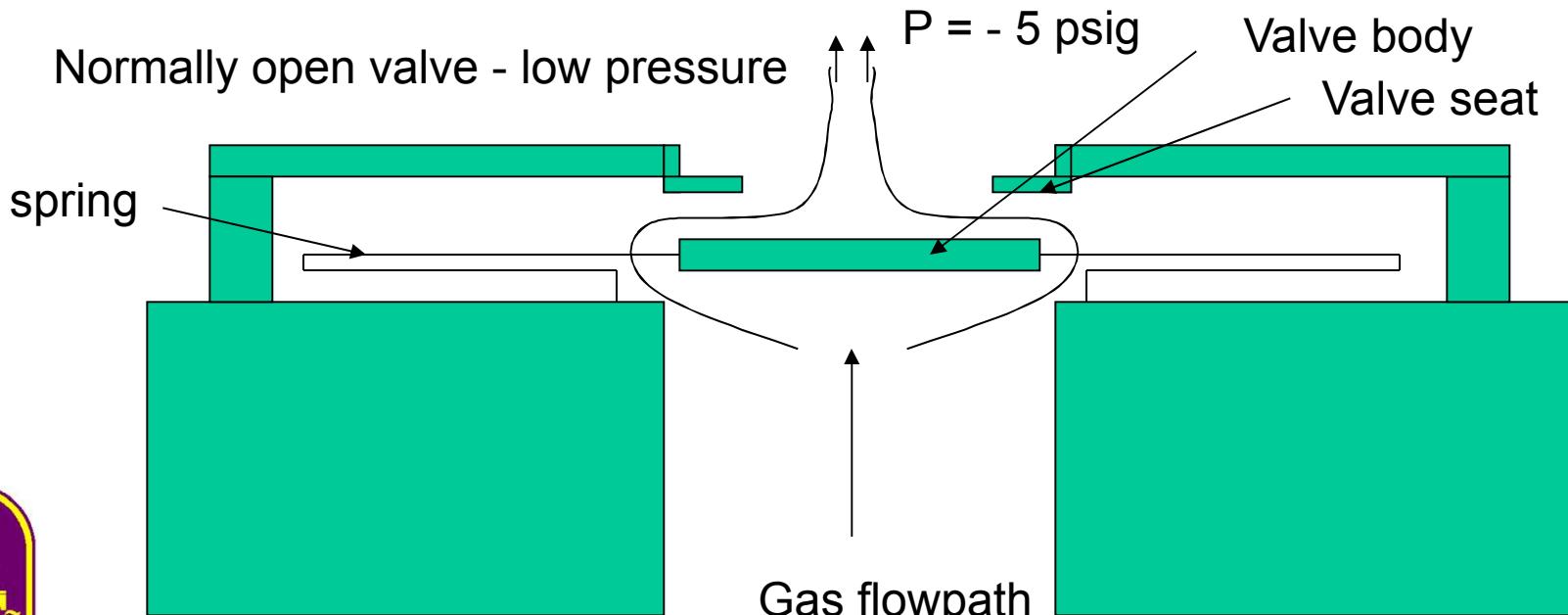


Exploded view from the bottom



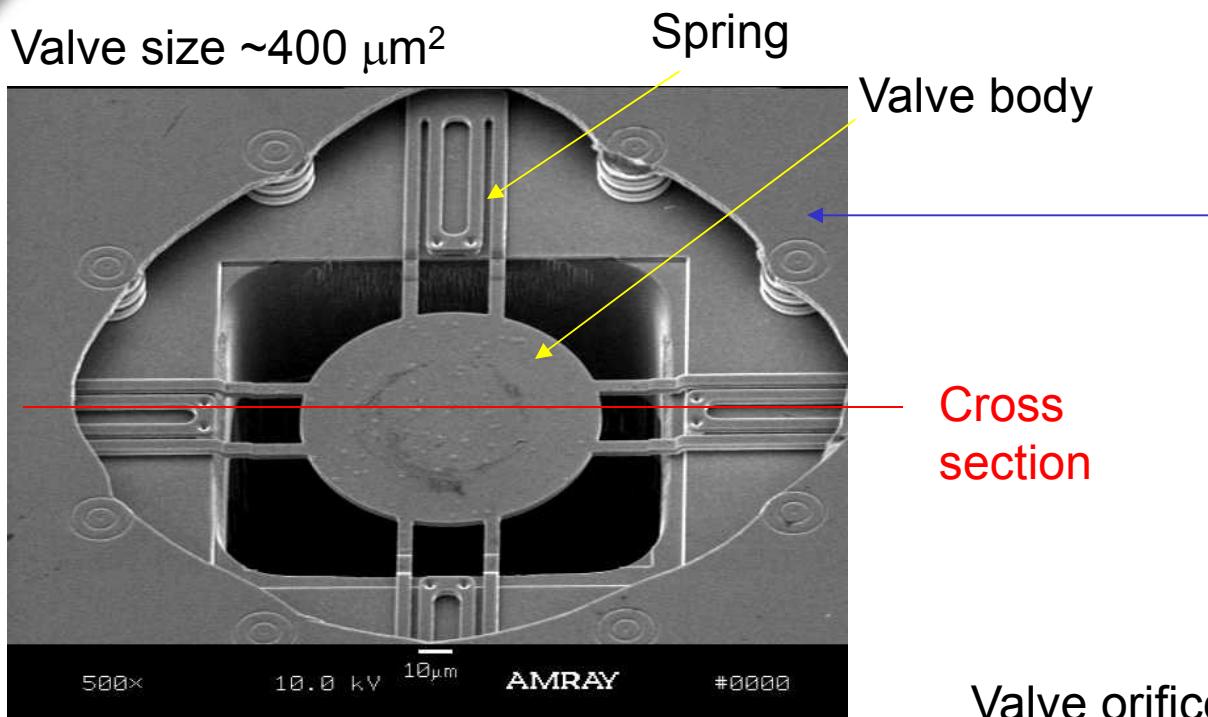
Passive Offset Check Valve design concept (normally open valve)

- Open one-way at low pressures
- Closed *in the same flow direction* at higher pressures
- A check valve with an offset.
- Our design uses a soft spring with properly selected stiffness, matched to:
 - Pressure requirement
 - Flow requirement
 - Orifice size



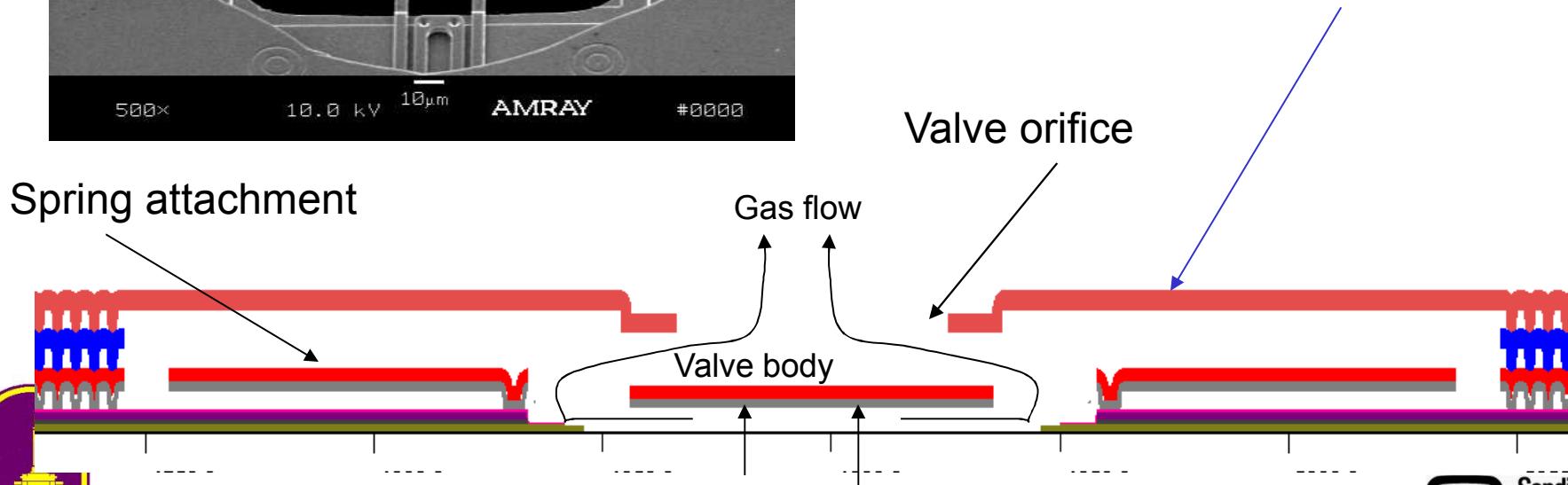
Valve 2 - SUMMiT™ design and fabrication

Valve size $\sim 400 \mu\text{m}^2$



Upper poly-Si layer, which defines the valve orifice, is cut away in the micrograph

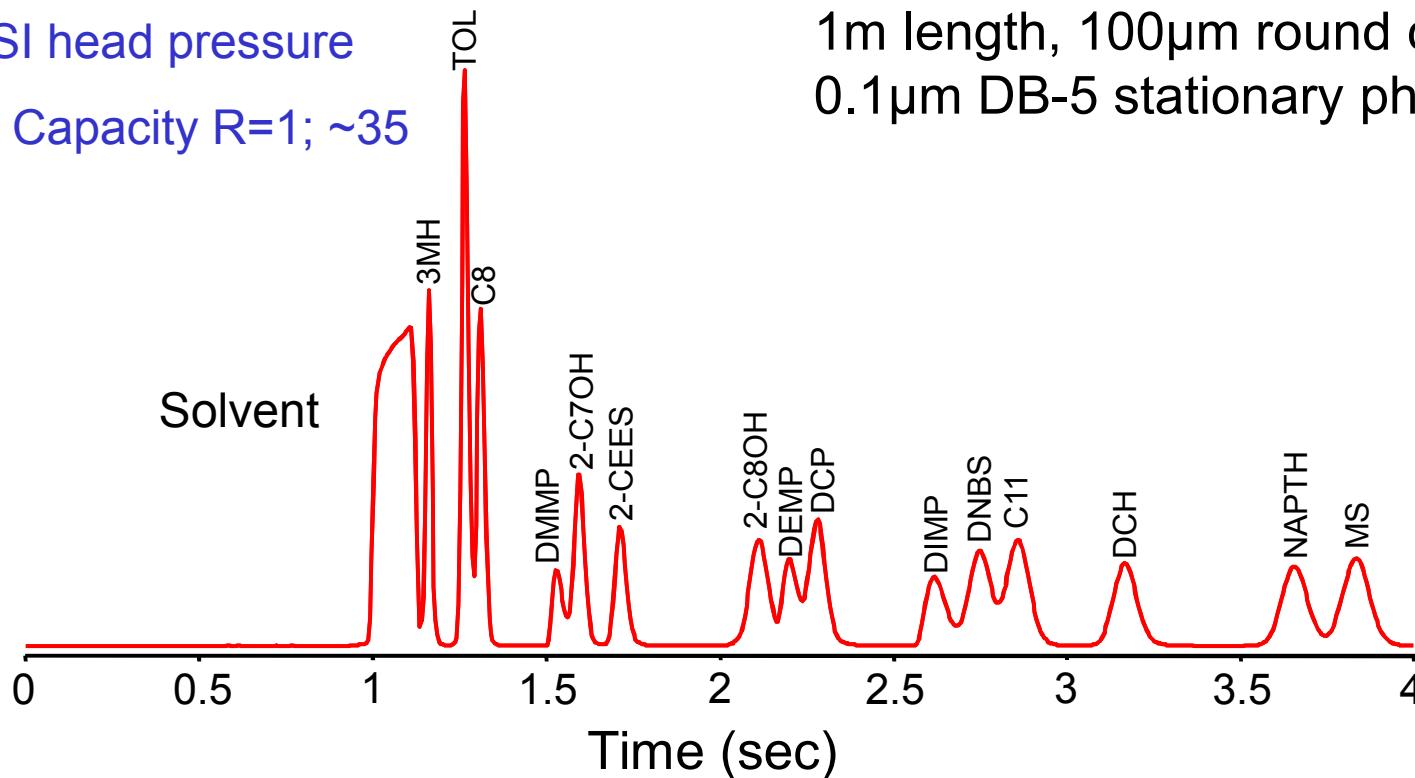
Spring attachment



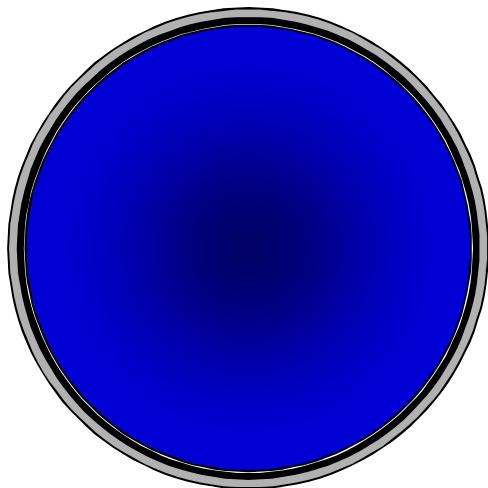
Separation of 16 Compounds in < 4 sec

- Temperature Programmed from 59 to 87 °C
- 30 PSI head pressure
- Peak Capacity R=1; ~35

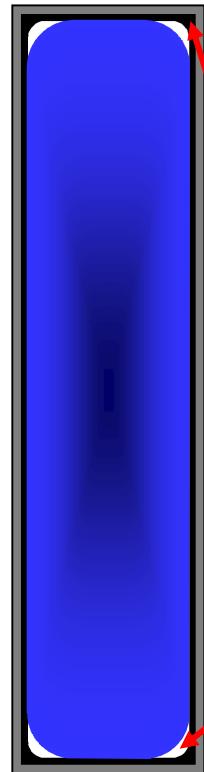
8 CWA simulants
8 interferents
1m length, 100µm round column
0.1µm DB-5 stationary phase



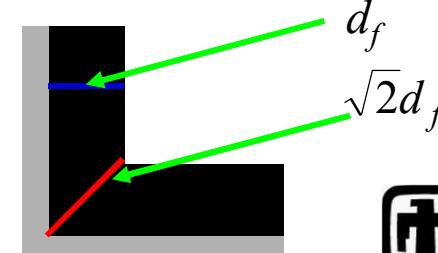
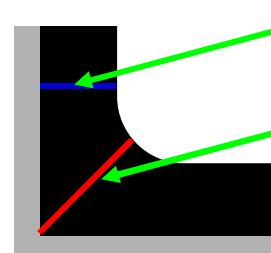
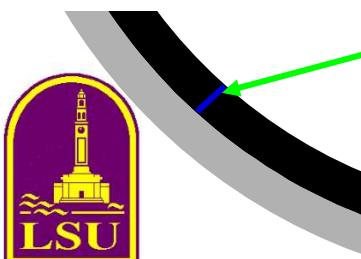
Round vs. HARM columns



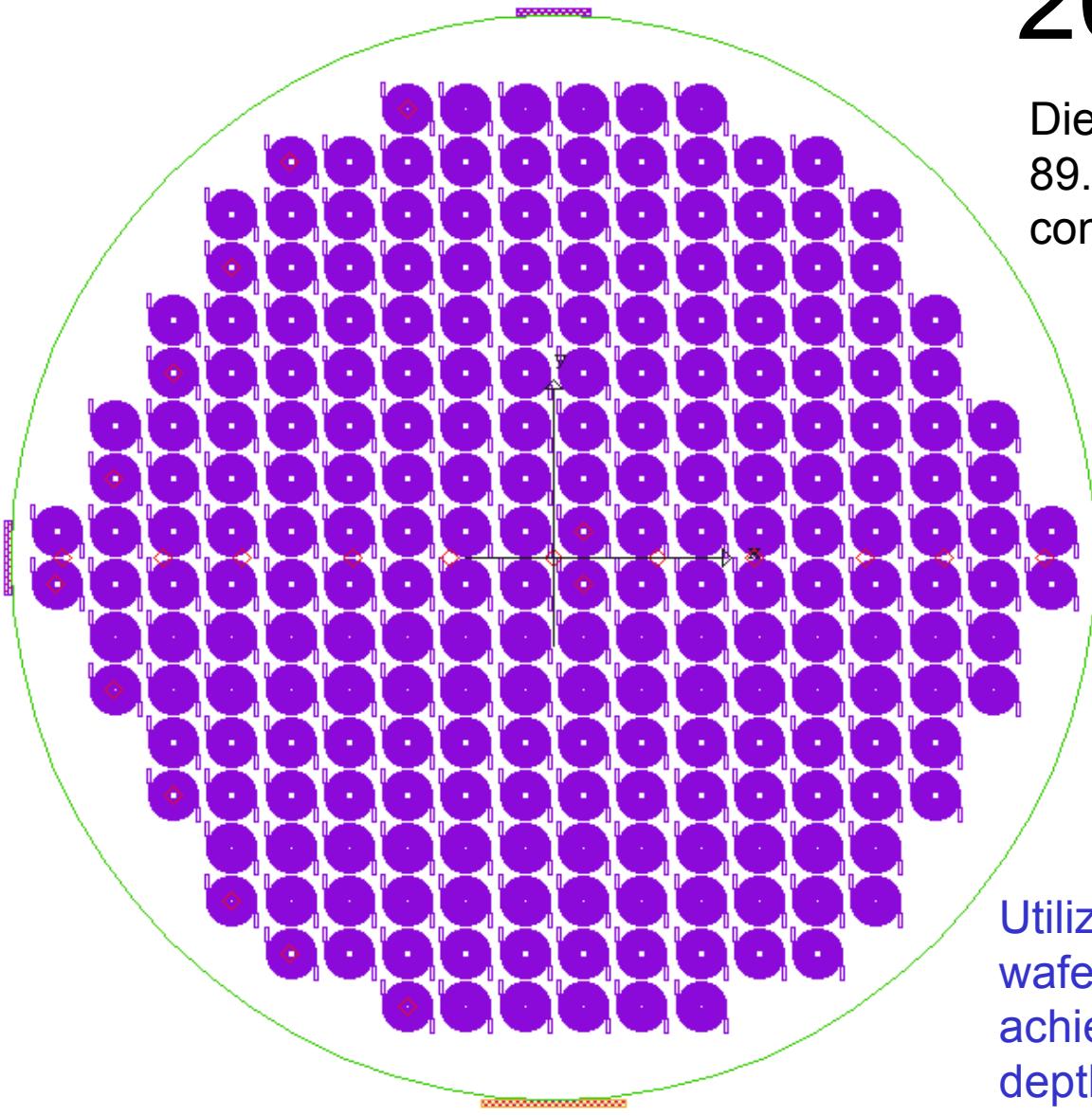
- Flow restriction and performance limited by radius
- Film deposition is uniform



- Flow restriction controlled by height
- Performance limited by width
- End effects
 - Film deposition often results in thicker phases in the corner
 - Dead spaces in corners



2090 GC



Die 1: 20 um wide, 20 um wall, 89.16 cm length between edge connections; 98 occurrences

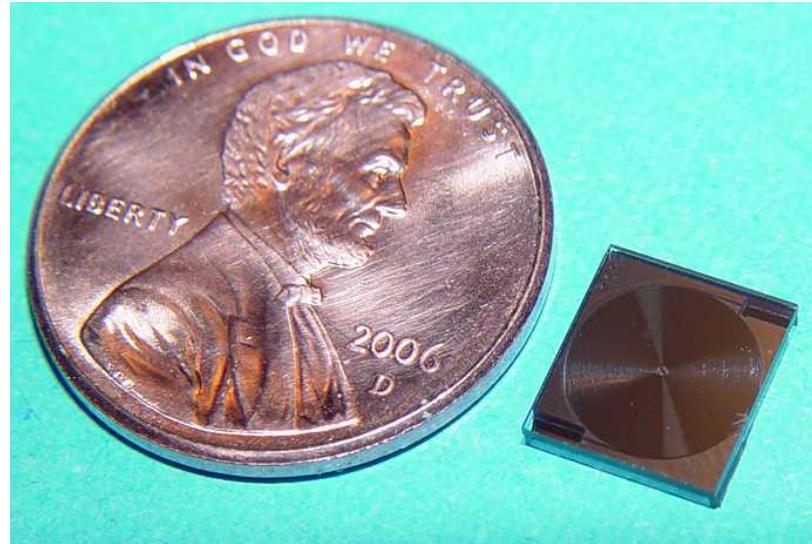
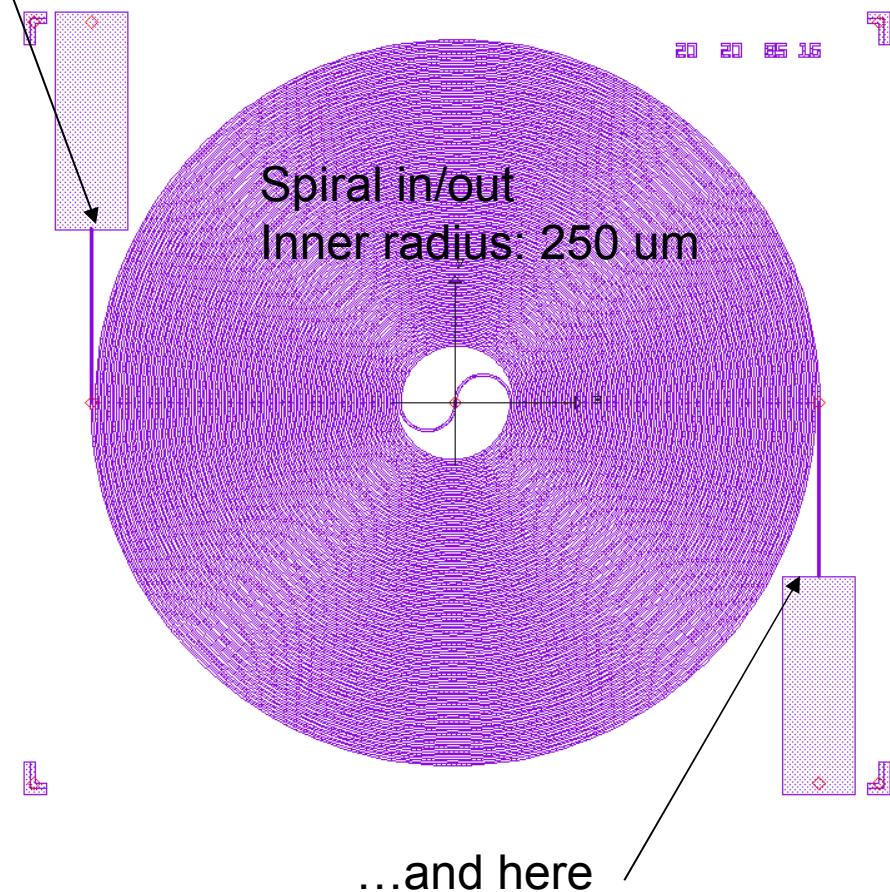
Die 3: 20 um wide, 30 um wall, 73.58 cm length; 68 occurrences

Die 2: Like Die 1 with slight taper before edge connections; 94 occurrences

Utilize BOX layer of SOI wafer as etch stop to achieve required column depths

Stated lengths
are measured
between here...

Sample Closeup: Die 1 fabricated on 20 um SOI (1 um BOX, 650 um Si)



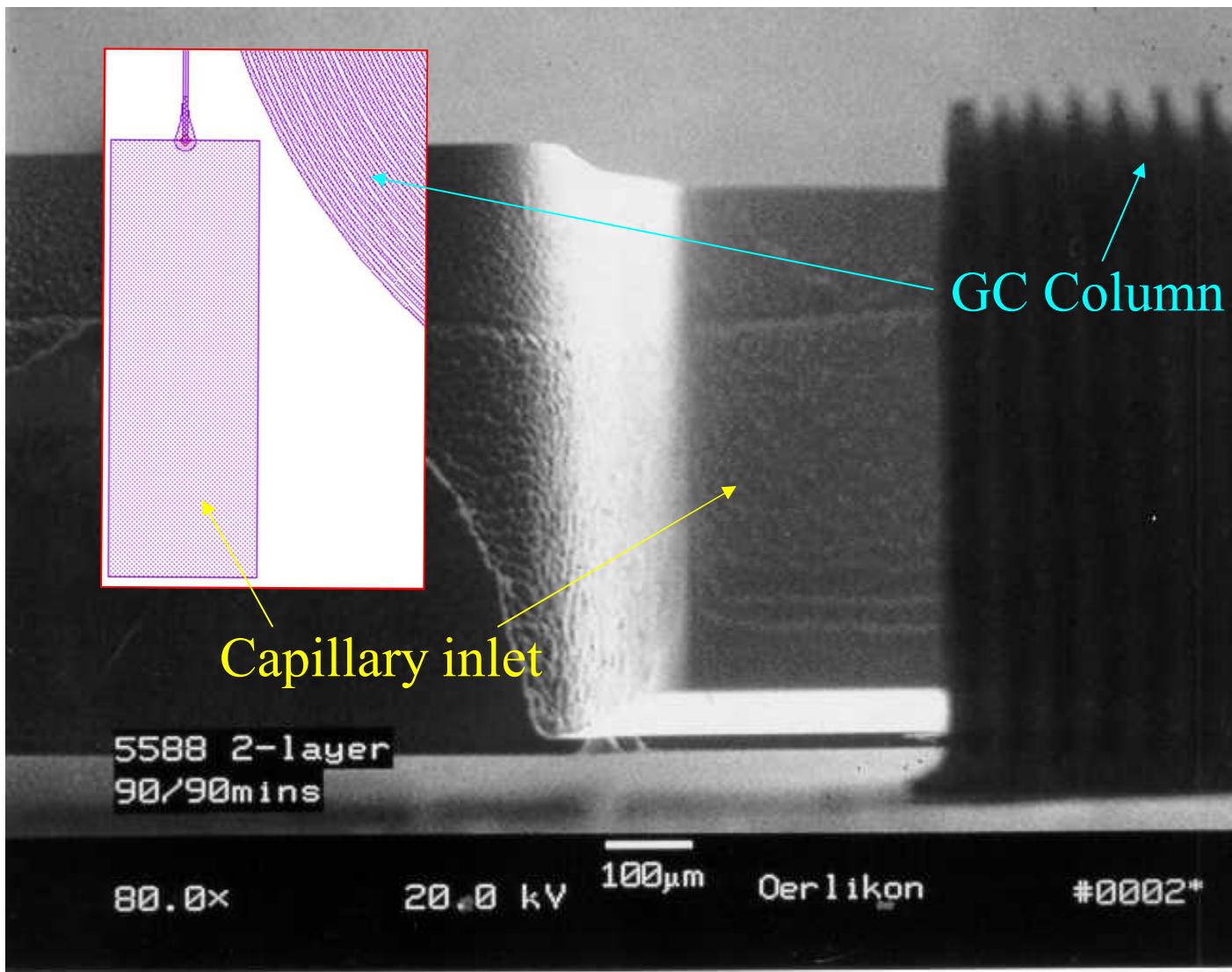
Die2 has a
slight taper

$$C_{tot} = 0.097 \frac{J}{K}$$



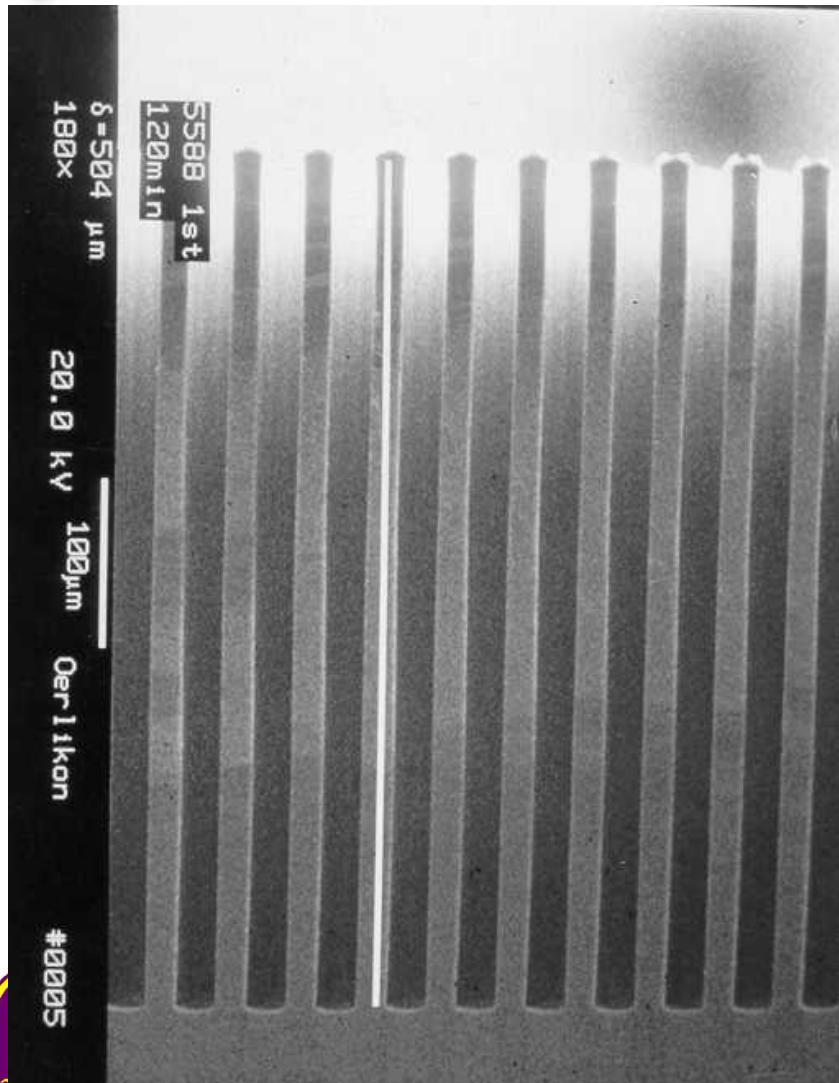
Delay layer has arrived and is awaiting processing

2090 GC test wafer - SEM

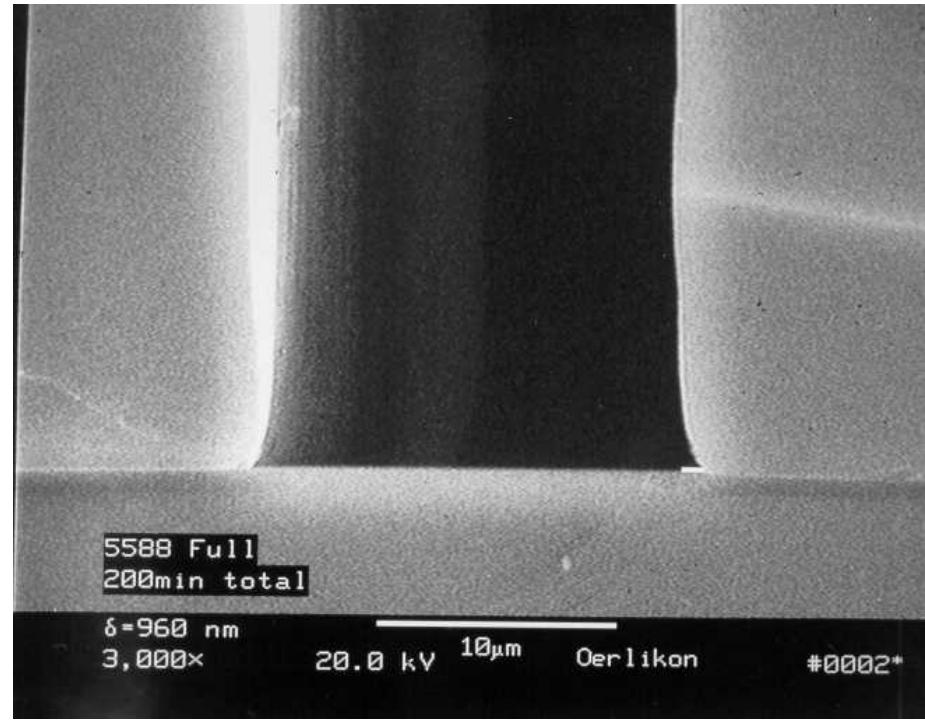


2090 GC test wafer - SEM

Column walls (first etch)

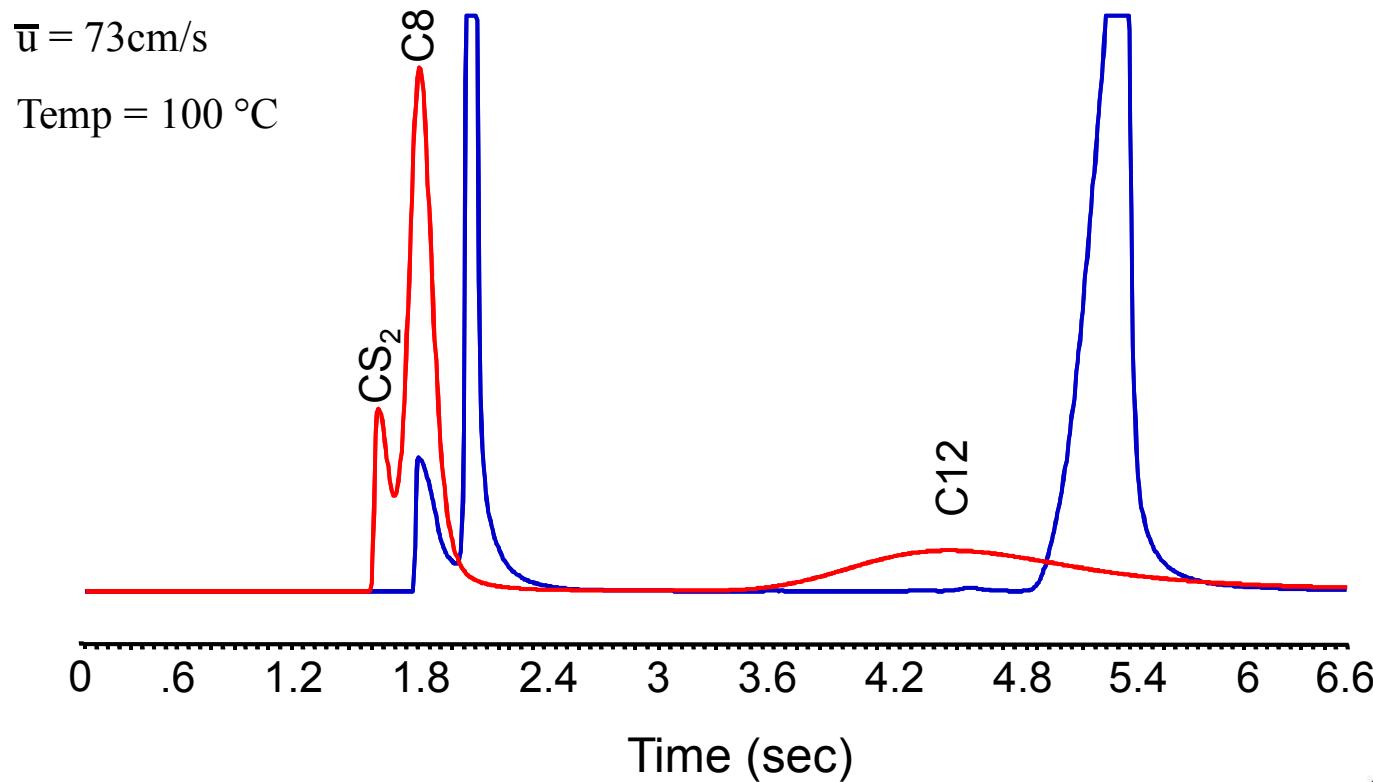


Bottom of column (2nd etch)

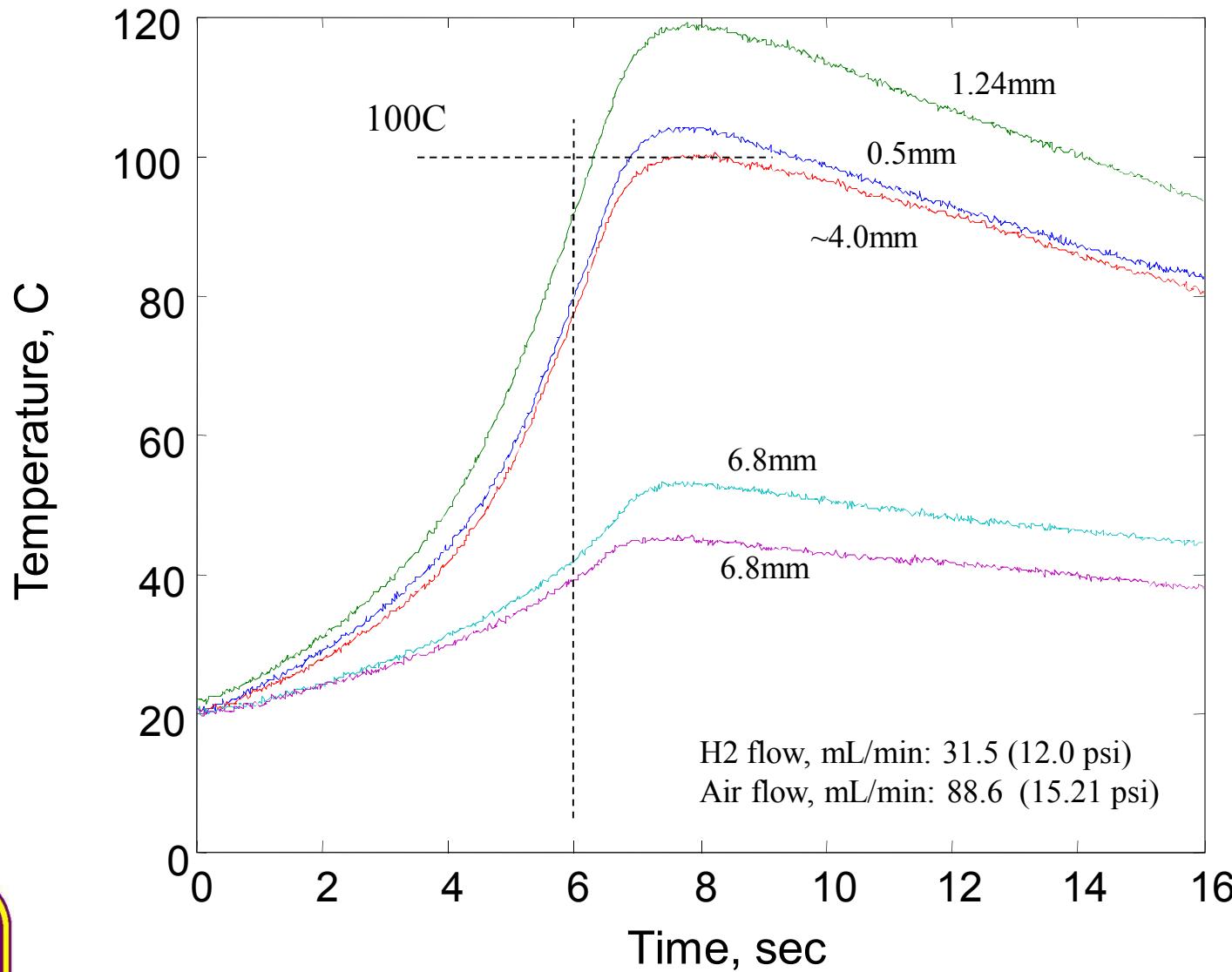


Coated Microcolumn Performance

- 1 m length of 0.1 μ m RTX-1 100 μ m
- 20 μ m x 400 μ m 90cm coated with ~30nm PDMS



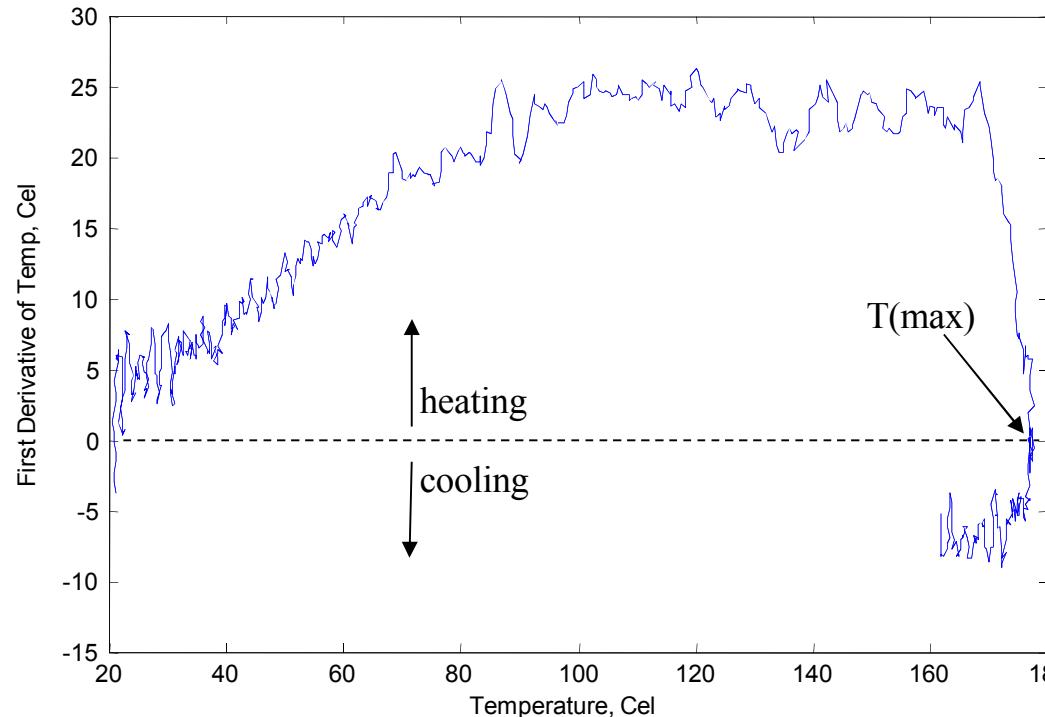
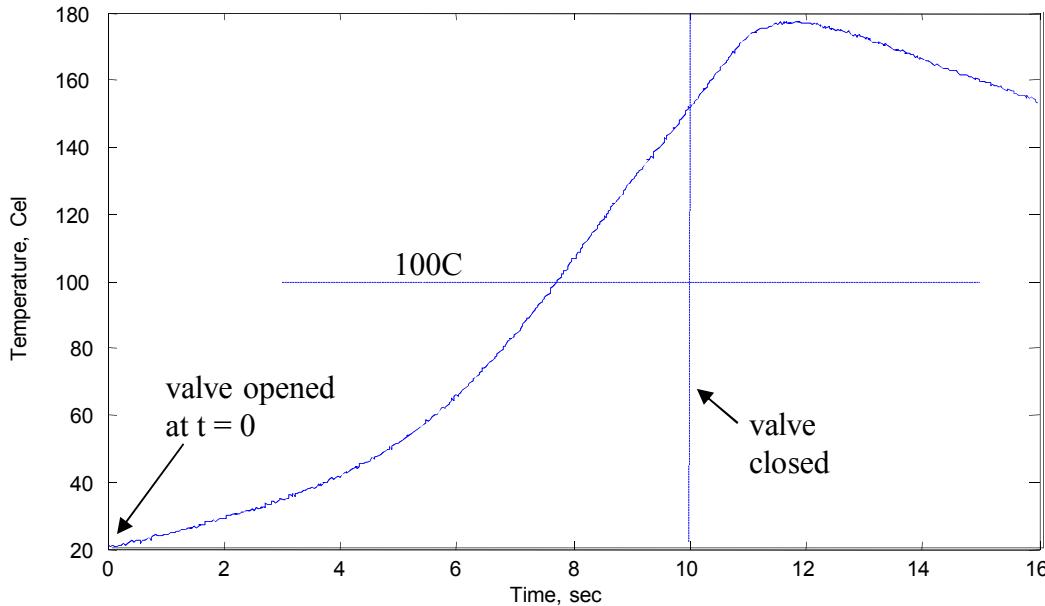
Example data, 2090 GC autocatalytic heating



Catalytic GC Heating

- Fuel autoignites
- Thermocouple T lags fuel valve switching
- Efficiency $\sim 25\%$, can be improved with “burner” design

dT/dt vs.
T

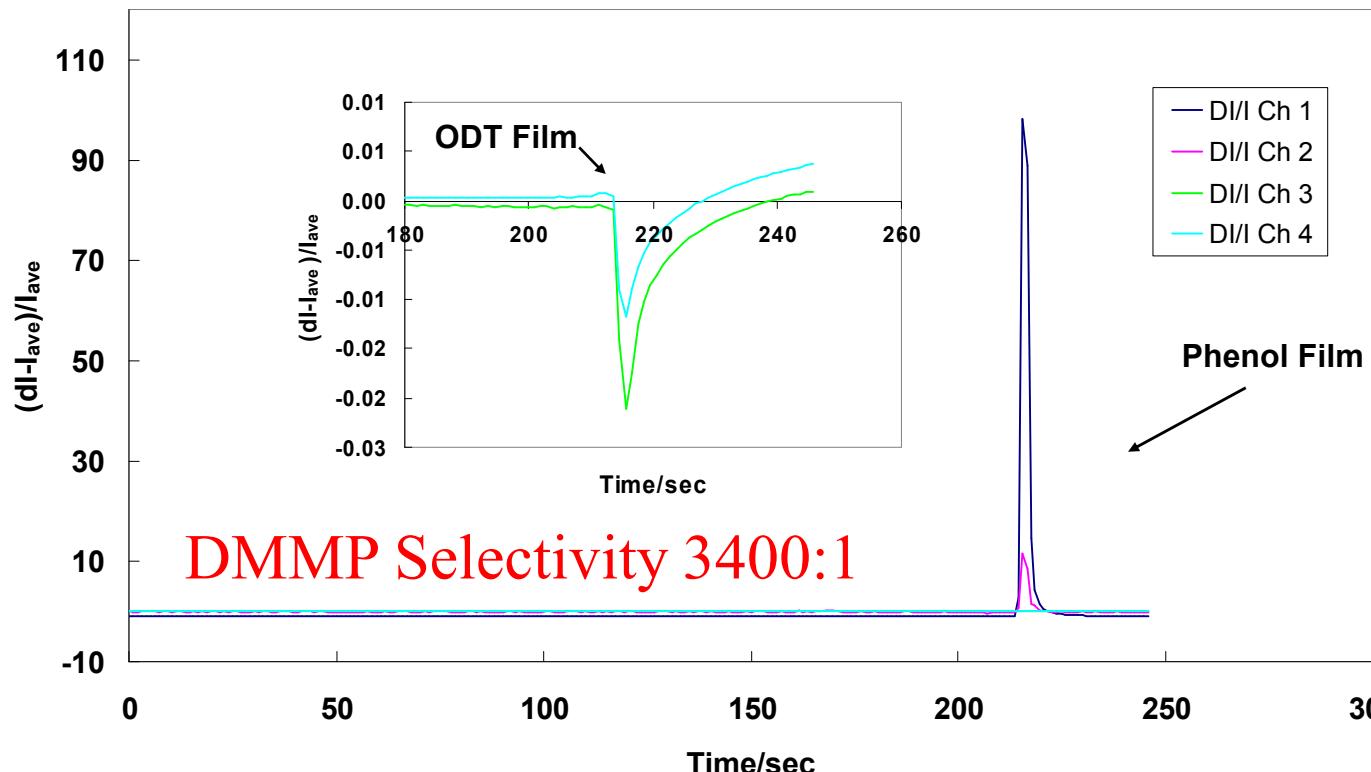


Initial Vapor sensing of DMMP using a protected phenol

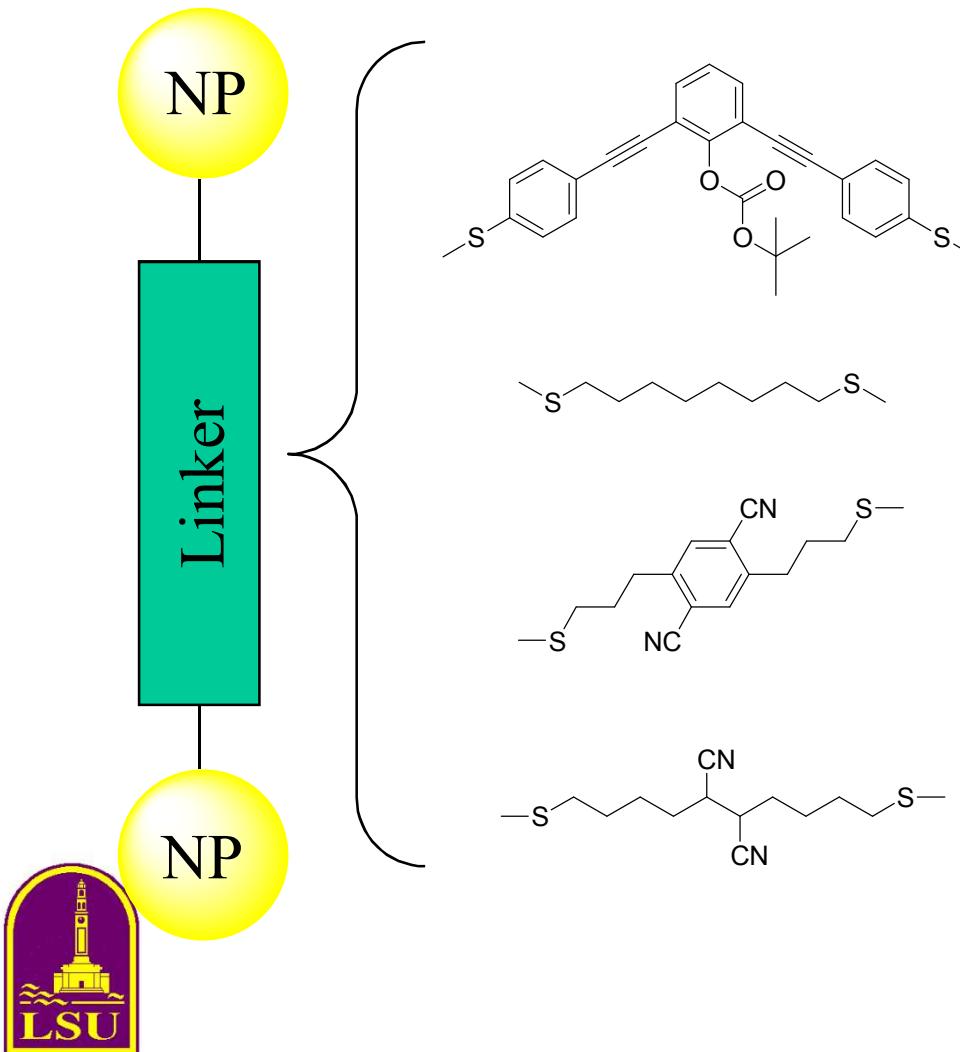
Our initial observations during exposure to DMMP show:

- Protected phenol-Au films have dramatically increased conduction (molecular electronic effect)
- Control ODT-Au films have a slight decrease in conduction (swelling)
- 10⁻⁴ J per detector channel per analysis!**

DMMP vapor from Tenax PC using Boc Protected Phenol Molecule as Ch 1 and Ch 2 and ODT as Ch 3 and Ch 4 both with Au nanoparticles



Additional Sensor Channel Candidates

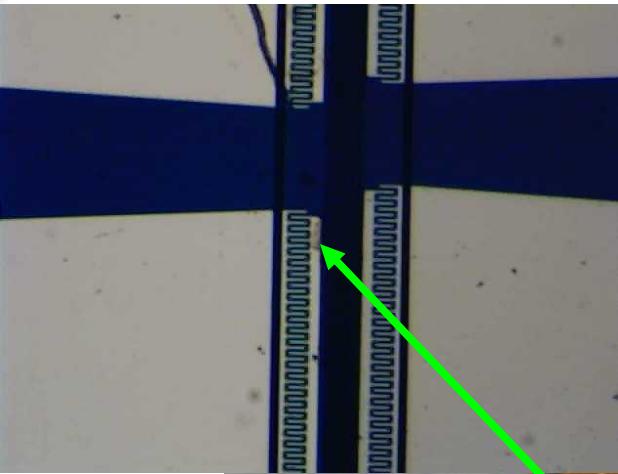


- Phosphonate-selective
- Electron hopping?

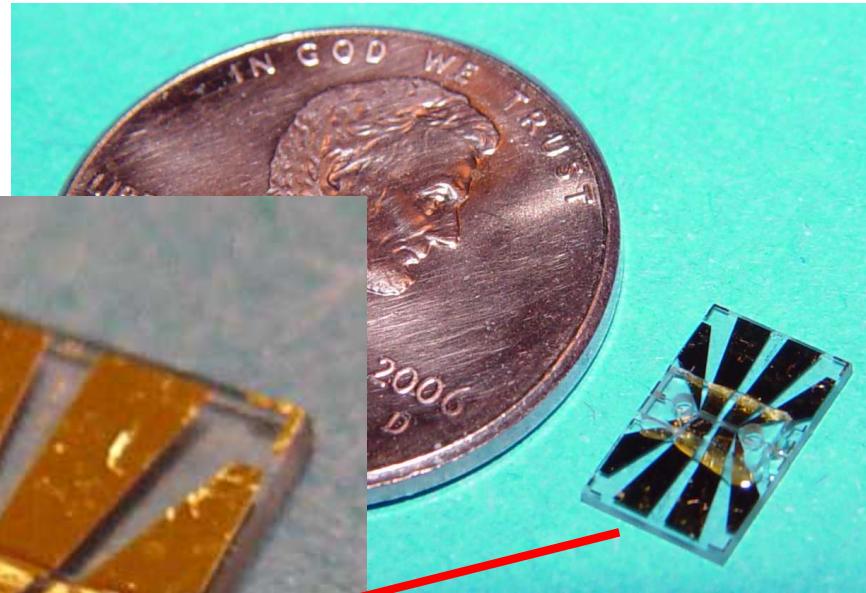
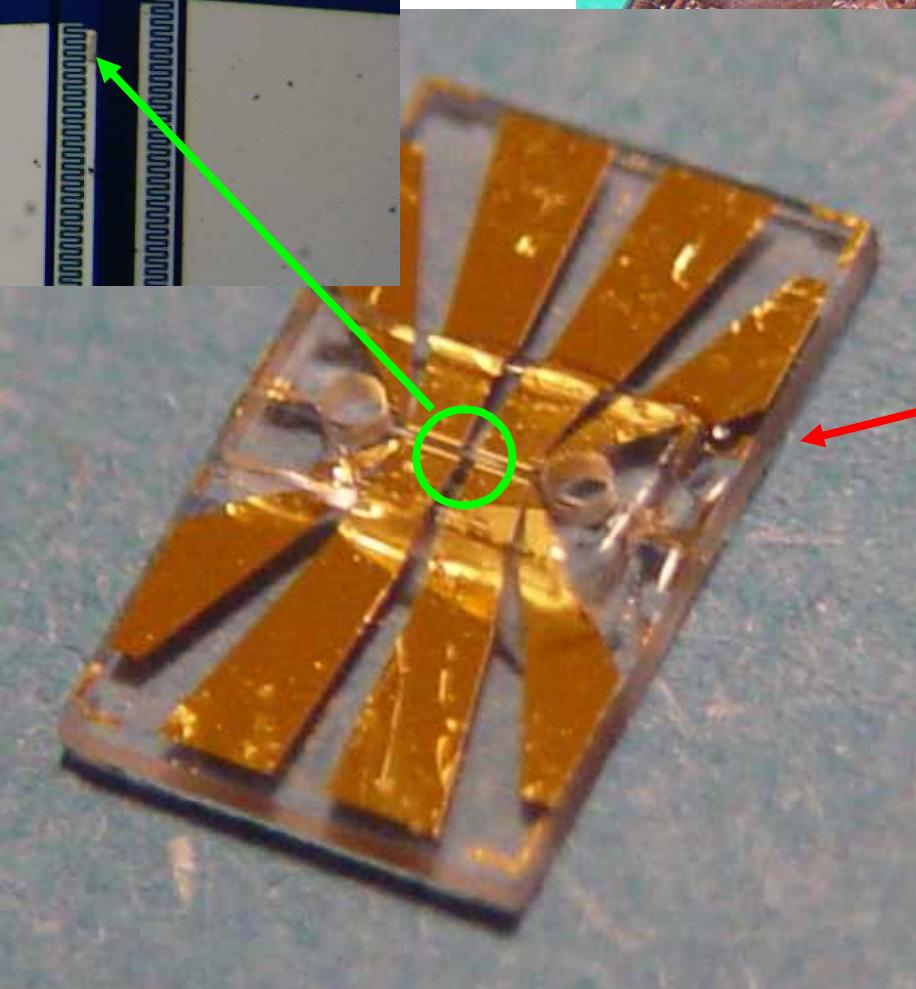
Swelling mechanism, nonpolar

- Swelling mechanism
- Vary polarity, polarizability
- Changing partition coefficients adds information to array response, increasing analytical power

Nanoparticle IDT Arrays



Two quartz nanoparticle IDT chips covered by a flow lid



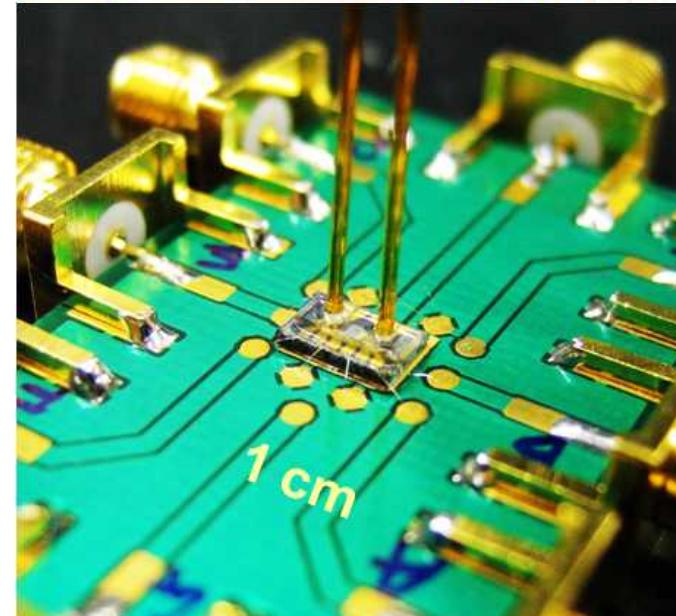
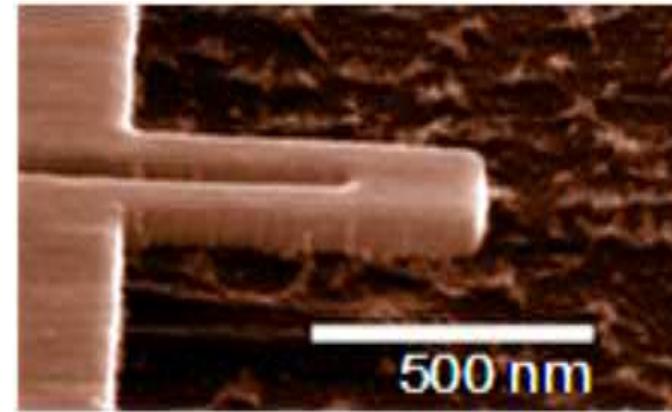
0.5 mm thick glass with 685 micron capillary holes



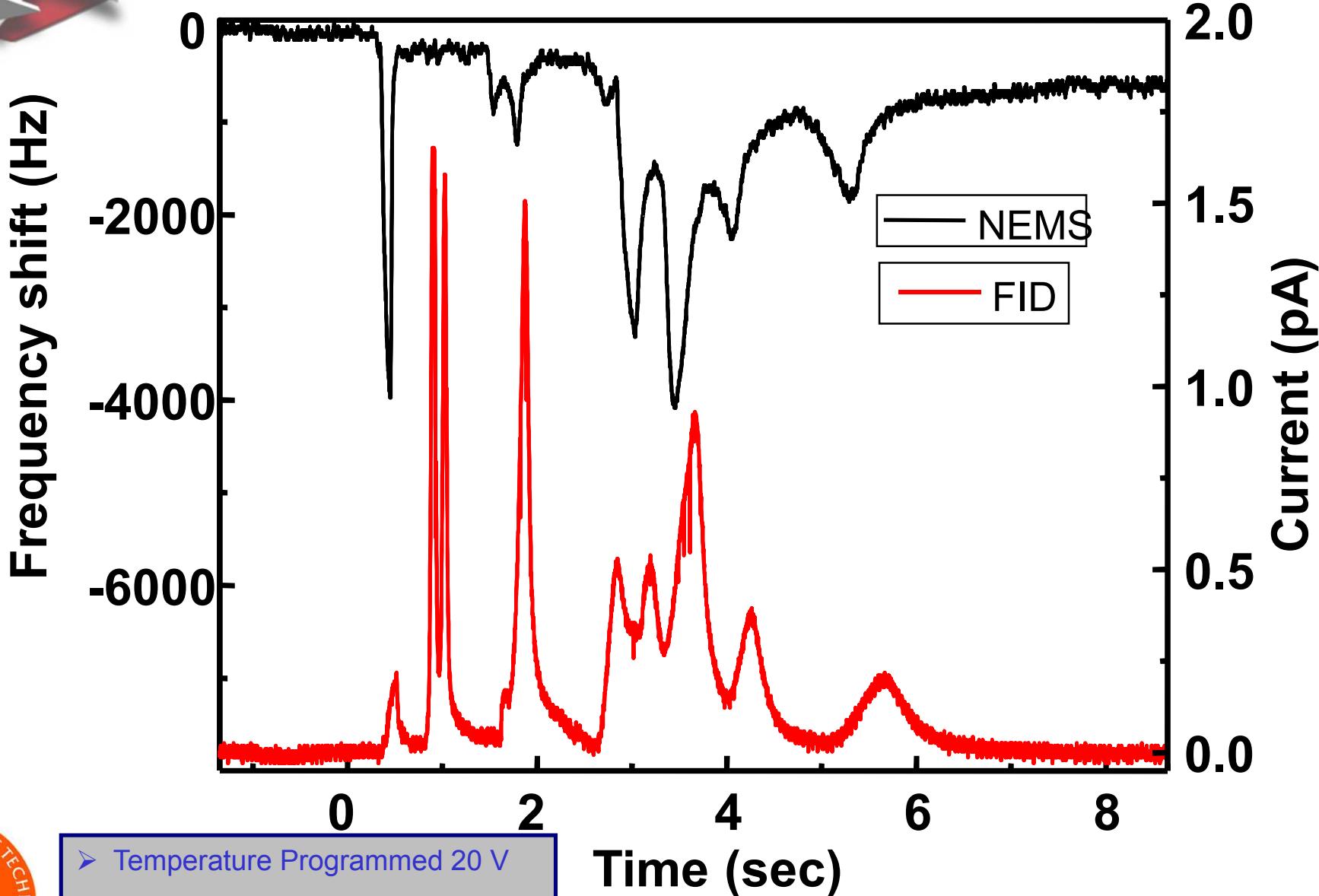


CalTech - NEMS Cantilever Resonators for GC Detection

- **100 zg** Noise floor at ambient temperature and pressure
- Low Power $< 1\mu\text{W}$
- High Frequency $> 1\text{GHz}$
- High Q values even in ambient air because of low active mass



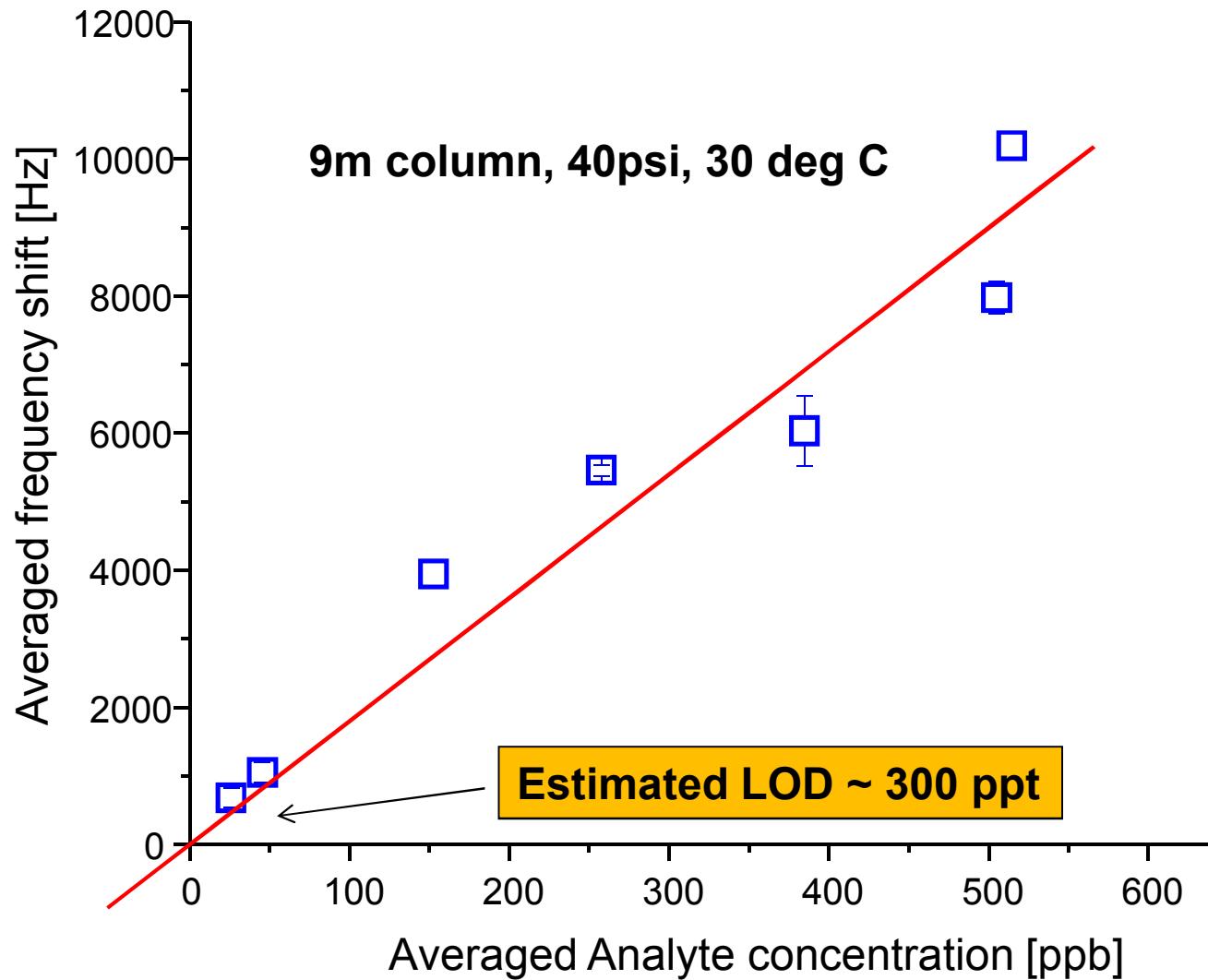
Fast GC with NEMS: 14 peaks in 6 seconds



- Temperature Programmed 20 V
- 30 PSI head pressure
- 8 simulants, 6 interferents

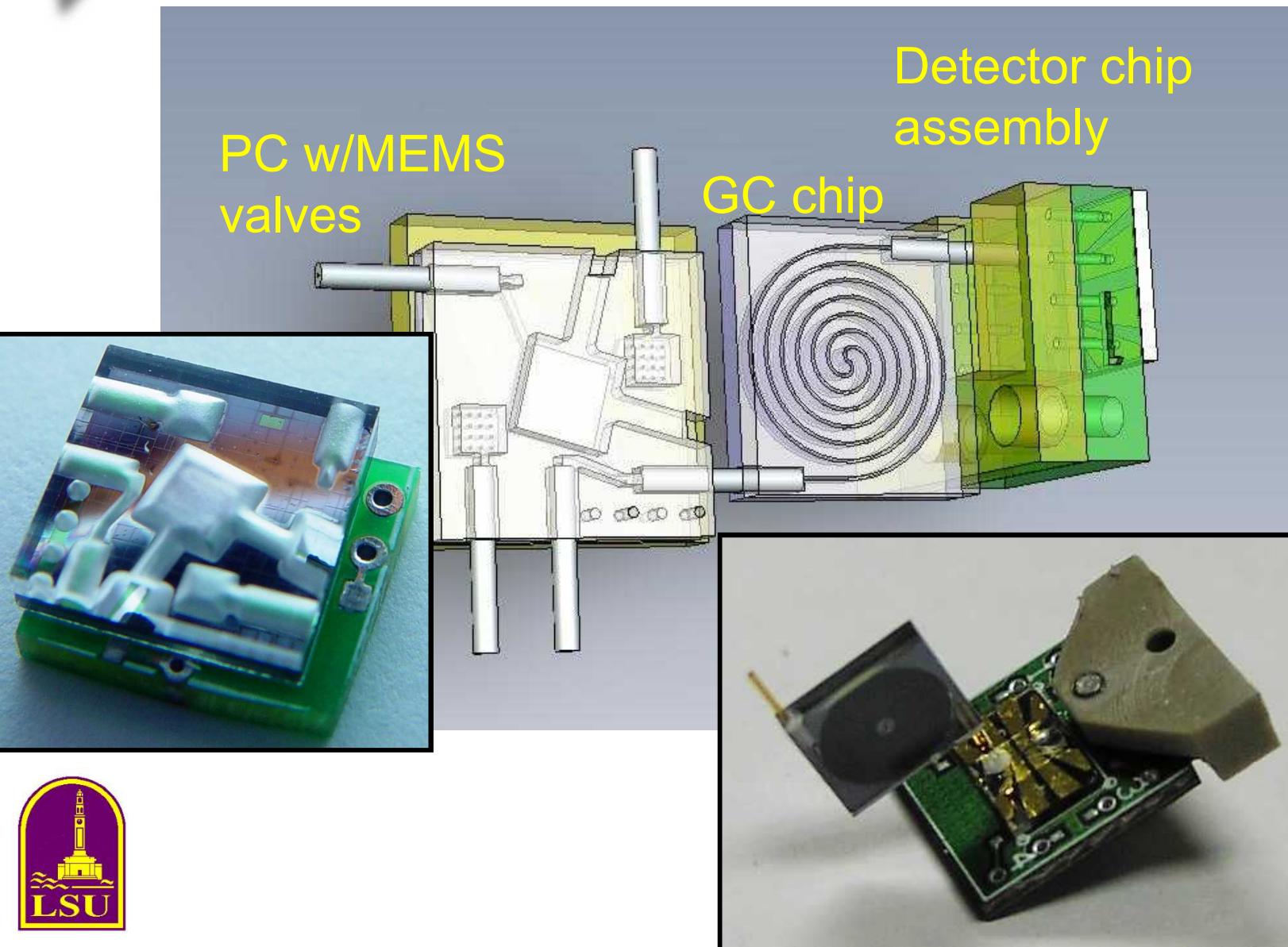


Detector Response



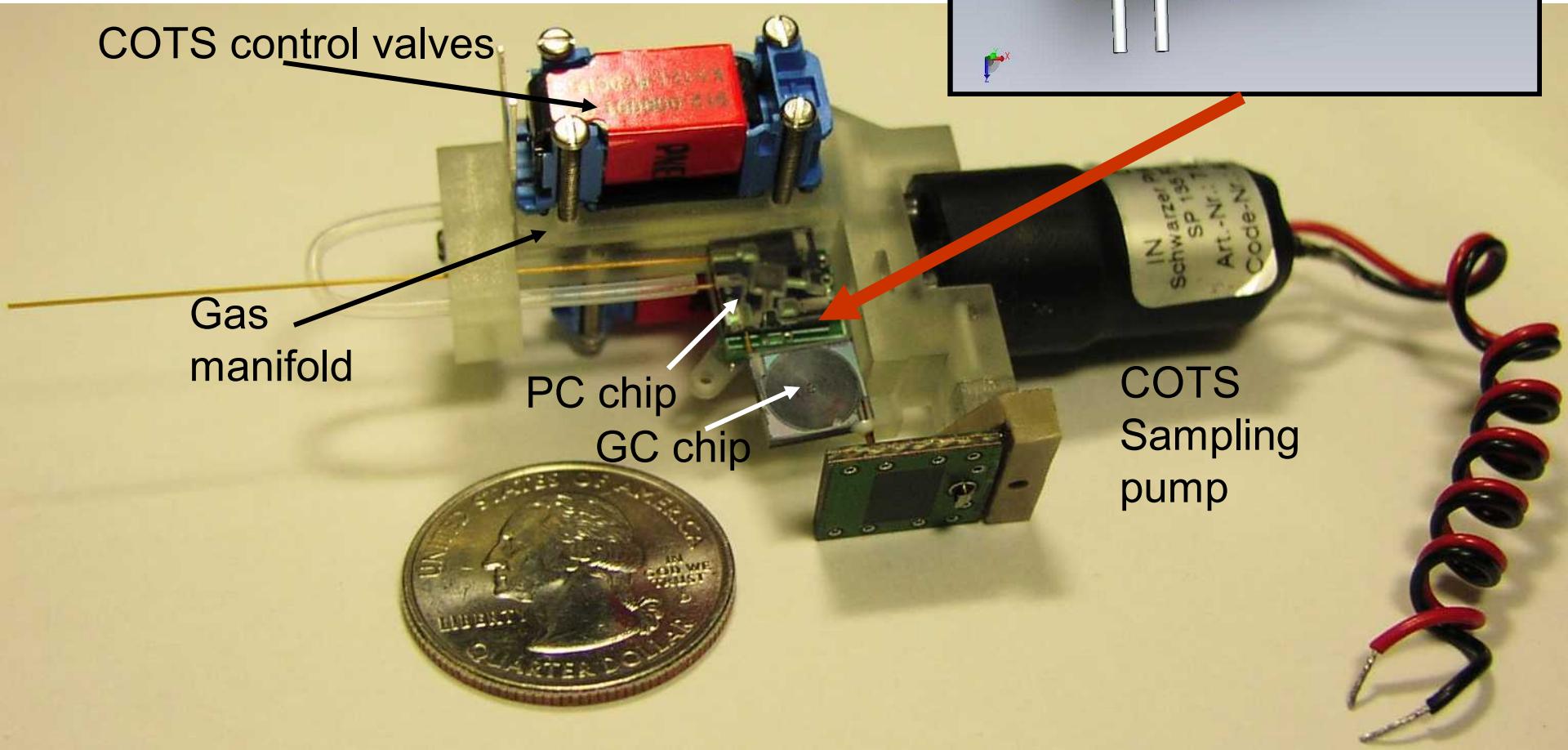


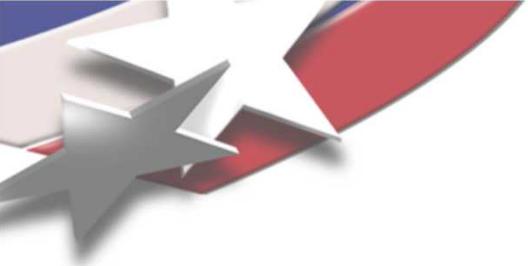
MicroFluidic Sub-Assembly



Total Fluidic System Assembly

Micro Fluidic Assembly





Future Work

- Modify fabrication of column structures to increase yield and minimize “grass” at the bottom of the high aspect channel structures
- Coat and test integrated PC and valve structure
- System testing

